

ABSTRACT OF DISCLOSURE

The present invention discloses a method of manufacturing circuit devices 10 with arbitrary external shapes, comprising the steps of: forming, on a conductive foil 30, conductive patterns 11 constituting circuit devices 10 of the same type or different types; affixing circuit elements 12 onto conductive patterns 11; molding with insulating resin 13 so as to cover circuit elements 12; and using a laser to cut insulating resin 13 at locations of the outer peripheral part of each circuit device 10 that are in accordance with a desired shape to thereby perform separation into each of circuit devices 10. Circuit devices 10 with arbitrary shapes can thus be manufactured and circuit devices that accommodate the shapes of the frames of sets can be provided.